Spec. No.: FMC-K-HTS-0001 /7

Date: 2017. 1. 10

# Specification

Title: CHIP FUSE; RECTANGULAR TYPE

Style: FMC10, 16

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

Product specification contained in this specification are subject to change at any time without notice If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Note: Stock conditions

Temperature:  $+5^{\circ}C \sim +35^{\circ}C$ Relative humidity:  $25\% \sim 75\%$ 

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

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#### 1. Scope

1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of FMC10, 16.

#### 1.2 Applicable documents

UL248-1-2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

## 2. Classification

Type designation shall be the following form.

1 Chip fuses; rectangular type

2 Size



3 Rated current

## 4 Optional code

Symbol	Optional code	
AB		
WB	Standard	
WH		

5 Packaging form

99	
В	Bulk (loose package)
TH	Donor toning
TP	Paper taping

# 3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1-00 and CSA C22.2, No. 248.14-00

The file number to be designated by UL and C-UL shall be as follows: E176847



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## 4. Rating

The ratings shall be in accordance with Table-1.

## 4.1 Optional code: AB

Table-1(1)

	Rated current		Internal resistance value	Rated	Breaking	Time / current characteristic		
Style	Symbol	(A)	Marking symbol	(m $\Omega$ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	240	DC24			4 h min. 5 s max. 0.2 s max.
	751	0.75	Α	140		DC24 35	100% 200% 300%	
	102	1.0	L	95				
FMC10	132	1.25	М	73				
1 IVIC 10	152	1.5	Η	60				
	202	2.0	S	41				
	252	2.5	T	32				
	302	3.0	R	25				

## 4.2 Optional code: WB

Table-1(2)

	Rated current		Internal resistance value	Rated	Breaking	Time / current characteristic		
Style	Symbol	(A)	Marking symbol	(m $\Omega$ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	260				
	751	0.75	Α	140				
	102	1.0	L	110	DC22 25			
	132	1.25	М	80		C32 35	100% 200% 300%	4 h min. 5 s max. 0.2 s max.
FMC16	152	1.5	Η	65				
FIVIC 10	202	2.0	S	45	DC32			
	252	2.5	Т	32				
	302	3.0	R	26				
	402	4.0	Χ	18				
	502	5.0	Υ	14				

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## 4.3 Optional code: WH

Table-1(3)

0.1	F	Rated curre	ent	Internal resistance value	Rated	Breaking	Time / current characteristic	
Style	Symbol	(A)	Marking symbol	(m $\Omega$ max.)	voltage (V)	-   ,	Current	Pre-arcing time
	501	0.5	<u>F</u>	250				
	751	0.75	<u>A</u>	150				
FMC10	102	1.0	<u>L</u>	100				
	132	1.25	M	70				
	152	1.5	<u>H</u>	60			100%	4 h min.
	202	2.0	<u>S</u>	40	DC24	35	200%	5 s max.
	252	2.5	Τ	30			300%	0.2 s max.
	302	3.0	<u>R</u>	25				
	322	3.15	J	24				
	402	4.0	<u>X</u>	18				
	502	5.0	<u>Y</u>	14				
	501	0.5	OF	400				4 h min.
	631	0.63	OI	300				
	751	0.75	OA	210				
	801	8.0	OK	180				
	102	1.0	OL	115				
	132	1.25	OM	90			100%	
FMC16	152	1.5	OH	70	DC32	35	200%	5 s max.
1 101010	162	1.6	ON	60	D002	00	300%	0.2 s max.
	202	2.0	OS	50			00070	oiz o maxi
	252	2.5	OT	37				
	302	3.0	OR	28				
	322	3.15	OU	26				
	402	4.0	OX	18				
	502	5.0	OY	14				

4.4 Working temperature range: -55 to +125(°C)

## 5. Packaging form

The standard packaging form shall be in accordance with Table-2.

## Table-2

Symbol					Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	FMC10, 16		
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	FMC10		
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	FMC16		

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## 6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

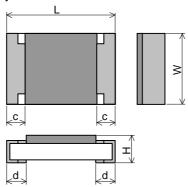


Figure-1

Table–3 Unit: mm

Style	Optional code	L	W	Н	С	d
EMC10	WH	1.010.05	0.510.05	0.35±0.05	0.210.40	0.05+0.40
FMC10	AB	1.0±0.05	0.5±0.05	0.38±0.05	0.2±0.10	0.25±0.10
FMC16	WB,WH	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.15	0.3±0.1

# 6.2 Net weight (Reference)

Style	Net weight(mg)
FMC10	0.6
FMC16	2

## 7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

## (Example)

Style	Optional code	Marking symbol	Content
FMC10	AB	S	FMC10 202 AB
FMC10	WH	<u>s</u>	FMC10 202 WH
FMC16	WB	S	FMC16 202 WB
FMC16	WH	OS	FMC16 202 WH

KAMAYA OHM

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#### 8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C  $\pm$  2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

8.2 The performance shall be satisfied in Table-4.

Table-4(1)

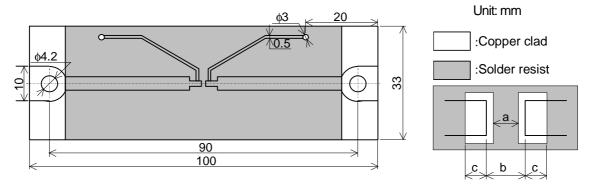
No	Toot itoms	Condition of test	Dorford	manaa raguiramanta
No.	Test items			mance requirements
1	Temperature rise	The fuse shall be mounted on the test substrate as shown in Figure–2.  Measurement temp.: 10 °C to 30 °C  Test current: Rated current  The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained.	75 °C max	
2	Time / current characteristic	The fuse shall be mounted on the test substrate as	Current	Pre-arcing time
		shown in Figure–2. Test current shall be applied for continuously.	100% 200% 300%	4 h min. 5 s. max. 0.2 s max.
3	Terminal bond strength of	JIS C 60068-2-21 Ue1	Change of	internal resistance:
	the face plating	The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: 3 mm(Among the fulcrums: 90 mm) Duration: $10 \text{ s} \pm 1 \text{ s}$	±10% No evidence of mechani damage.	
4	Resistance to soldering heat	Test by a piece. Temp. of solder bath: 260 °C ± 5 °C Immersion time: 10 s ± 1 s After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.  • Reflow soldering Pre–heating: 150 °C ~ 180 °C, 120 s max. Peak: 260 °C ± 5 °C, 10 s max. Reflow cycle: 2 times After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.	Change of internal resistance: ±10% No evidence of appearance damage	
5	Solderability	JIS C 60068-2-58 Test by a piece Flux: Rosin–Methanol Temp. of solder: bath: 235 °C ± 5 °C Immersion time: 2 s ± 0.5 s	The surface of terminal immerse shall be min. of 95 % covered win a new coating of solder.	
6	Rapid change temperature	JIS C 60068-2-14 Na The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles	Change of ±10% No evide damage	internal resistance: ence of appearance

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## 9. Test substrate



Style	а	b	С
FMC10	0.3	0.6	0.65
FMC16	0.6	1.0	0.5

# Figure-2 FMC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

## 10. Taping

10.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

10.2 Taping dimensions

10.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.

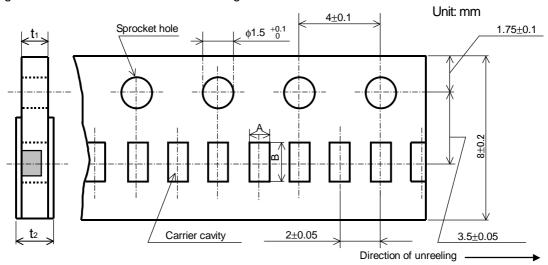


Figure-3

	Unit: mm			
Style	Α	В	<b>t</b> 1	t <sub>2</sub>
FMC10	0.65 +0.05	1.15 <sup>+0.05</sup> <sub>-0.10</sub>	$0.4 \pm 0.05$	0.5max.

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## 10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.

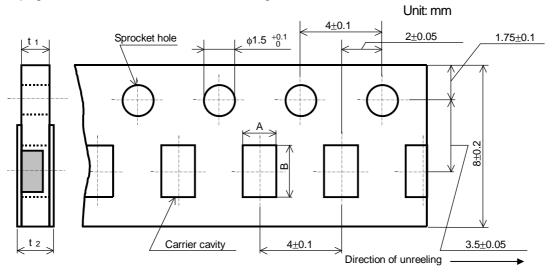


Figure-4
Table-6 Unit: mm

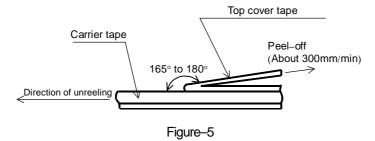
Style A B t<sub>1</sub> t<sub>2</sub>

FMC16 1.15±0.15 1.9±0.2 0.6±0.1 0.8 max.

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

The maximum number of missing components shall be one or 0.1%, whichever is greater.

8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



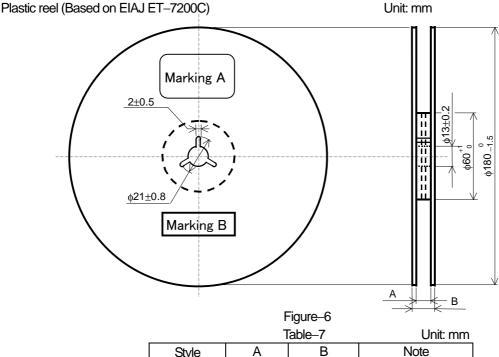
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#### 10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-6 and Table-7.



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	Table-7		Unit: mm
Style	Α	В	Note
FMC10, 16	9 +1.0	11.4±1.0	Injection molding
		13±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

## 10.4 Leader and trailer tape.

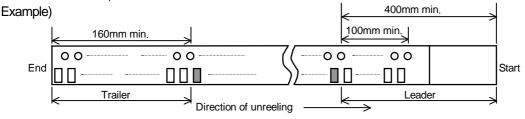


Figure-7

## 11. Marking on package

The label of a minimum package shall be legibly marked with follows.

# 11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C-UL recognized component mark 11.2 Marking B (KAMAYA Control label)

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## 12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

Nominal Derating

Nominal Derating ≤ 75% of Rated Current

\*FMC10 Optional code: WH, Rated current ≥ 3.15A: Nominal Derating ≤ 70% of Rated Current

• Temperature Derating

Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If FMC16 202WH (Rated Current 2.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current:  $2.0A \times (Nominal Derating: 75\% \times Temperature Derating: 80\%) = 1.2A$ 

## **Derating curve**

